

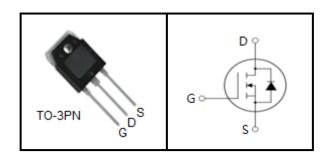
# **500V N-Channel MOSFET**

#### **FEATURES**

- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

#### **APPLICATIONS**

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)



Device Marking and Package Information			
Device	Package	Marking	
TMV28N50H	TO-3PN	V28N50H	



<b>Absolute Maximum Ratings</b> $T_C = 25^{\circ}C$ , unless otherwise noted			
Parameter	Symbol	Value	Unit
Drain-Source Voltage (V <sub>GS</sub> = 0V)	V <sub>DSS</sub>	500	>
Continuous Drain Current	I <sub>D</sub>	28	Α
Pulsed Drain Current (note1)	I <sub>DM</sub>	112	Α
Gate-Source Voltage	$V_{GSS}$	±30	<b>V</b>
Single Pulse Avalanche Energy (note2)	E <sub>AS</sub>	1350	mJ
Avalanche Current (note1)	I <sub>AR</sub>	16	Α
Repetitive Avalanche Energy (note1)	E <sub>AR</sub>	90	mJ
Power Dissipation (T <sub>C</sub> = 25°C)	P <sub>D</sub>	150	W
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~+150	°C

Thermal Resistance				
Parameter	Symbol	Value	Unit	
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	0.85	°C/W	
Thermal Resistance, Junction-to-Ambient	R <sub>thJA</sub>	60	30/00	



<b>Specifications</b> $T_J = 25^{\circ}$ C, unless otherwise noted						
Parameter	Symbol	<b>7</b> . 0 . III	Value			
		Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	500			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 500V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	μA
Gate-Source Leakage	I <sub>GSS</sub>	$V_{GS} = \pm 30V$			±100	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		4.0	V
Drain-Source On-Resistance (Note3)	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 14A		0.16	0.2	Ω
Dynamic				•		
Input Capacitance	C <sub>iss</sub>	V 0V		4550		pF
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0V,$ $V_{DS} = 25V,$		440		
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0MHz		60		
Total Gate Charge	$Q_g$			120		nC
Gate-Source Charge	$Q_{gs}$	$V_{DD} = 400V, I_{D} = 28A,$ $V_{GS} = 10V$		18		
Gate-Drain Charge	$Q_{gd}$	65		51		
Turn-on Delay Time	t <sub>d(on)</sub>			40		
Turn-on Rise Time	t <sub>r</sub>	$V_{DD} = 250V, I_{D} = 28A,$		70		ns
Turn-off Delay Time	t <sub>d(off)</sub>	$R_G = 25 \Omega$		180		
Turn-off Fall Time	t <sub>f</sub>			90		
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I <sub>S</sub>	T			28	Δ
Pulsed Diode Forward Current	I <sub>SM</sub>	T <sub>C</sub> = 25 °C			112	A
Body Diode Voltage	V <sub>SD</sub>	$T_J = 25^{\circ}\text{C}, I_{SD} = 28\text{A}, V_{GS} = 0\text{V}$			1.4	V
Reverse Recovery Time	t <sub>rr</sub>	$V_{GS} = 0V, I_{S} = 28A,$		480		ns
Reverse Recovery Charge	Q <sub>rr</sub>	di <sub>F</sub> /dt =100A /µs		8		μC

#### Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2.  $I_{AS}$  = 16A,  $V_{DD}$  = 50V,  $R_{G}$  = 25  $\Omega$ , Starting  $T_{J}$  = 25  $^{o}C$
- 3. Pulse Test: Pulse width ≤ 350µs, Duty Cycle ≤ 1%



ID, Drain Current (A)

## **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

Is, Source Current (A)

Figure 1. Output Characteristics ( $T_J = 25^{\circ}C$ )

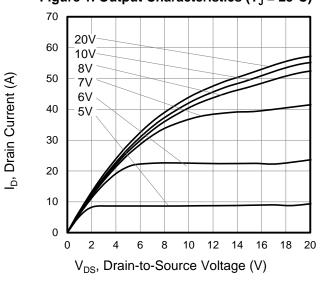


Figure 2. Body Diode Forward Voltage

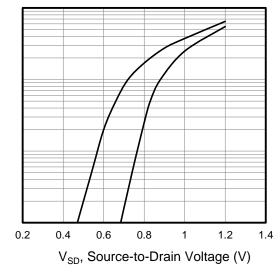


Figure 3. Drain Current vs. Temperature

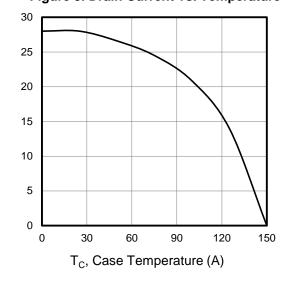


Figure 4. BV<sub>DSS</sub> Variation vs. Temperature

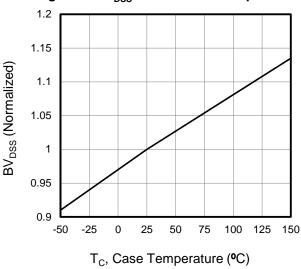


Figure 5. Transfer Characteristics

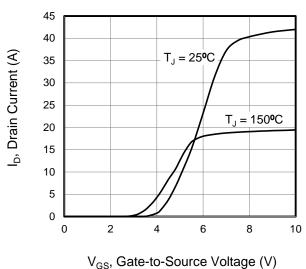
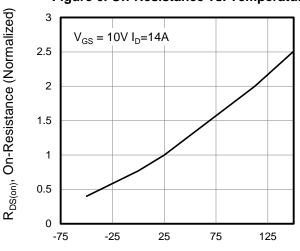
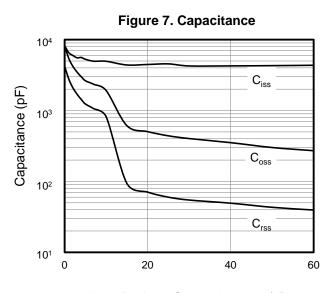


Figure 6. On-Resistance vs. Temperature

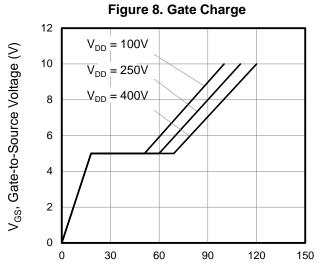


T<sub>J</sub>, Junction Temperature (°C)

# **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted



 $V_{DS}$ , Drain-to-Source Voltage (V)



Q<sub>q</sub>, Total Gate Charge (nC)



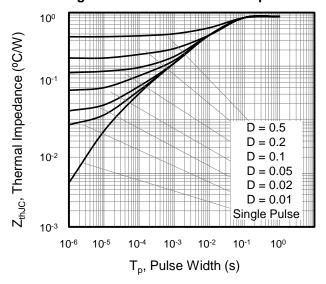


Figure A: Gate Charge Test Circuit and Waveform

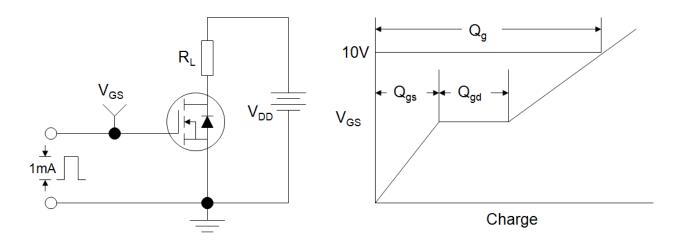


Figure B: Resistive Switching Test Circuit and Waveform

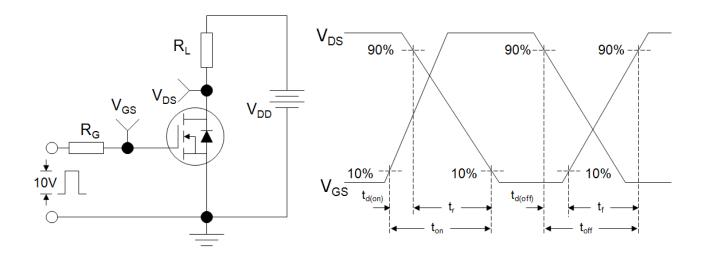
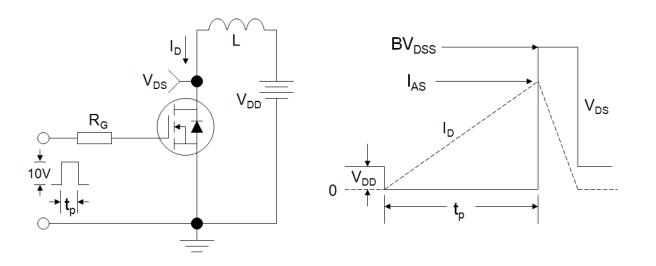
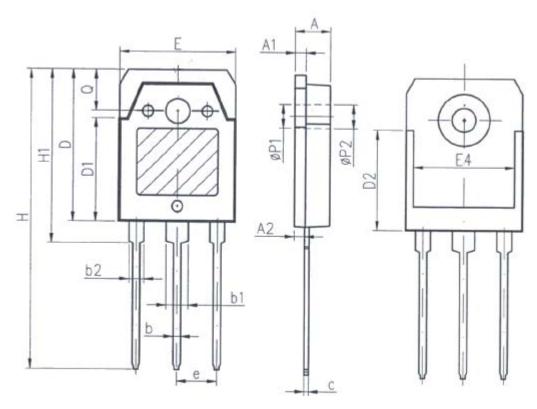


Figure C: Unclamped Inductive Switching Test Circuit and Waveform





# TO-3PN



Unit:mm			
Symbol	Min.	Max.	
Α	4. 6	5	
A1	1. 4	1. 65	
A2	1. 18	1. 58	
b	0.8	1. 2	
b1	2. 8	3. 2	
b2	1.8	2. 2	
С	0. 5	0. 75	
D	19. 6	20. 2	
D1	13. 55	14. 25	
D2	12. 9REF		
E	15. 35	15. 85	
E4	12. 6	-	
е	5. 45TYP		
Н	40. 1	40. 9	
H1	23. 15	23. 65	
P1	3. 2REF		
P2	3. 5REF		



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